

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Schaepkens et al.

Application No.: New Application

Filed: Herewith

For: REPLACEABLE PLATE EXPANDED THERMAL PLASMA APPARATUS
AND METHOD

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

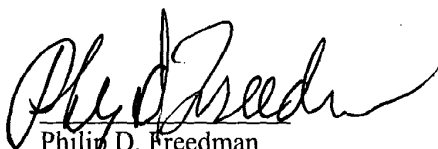
Sir:

Pursuant to 37 C.F.R. 1.56, the attention of the Patent and Trademark Office is hereby directed to the references listed on the attached Form PTO-1449. One copy of each reference is attached. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the references be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

No fee should be required. However, please credit or debit Deposit Account No. 500917 as needed to ensure consideration of the disclosed information. Two copies of this paper are attached.

Respectfully submitted,



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9/5, 2003

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| Form PTO-1449 US Dept. of Commerce (REV. 8-83) PATENT & TRADEMARK OFFICE | | | | ATTY DOCKET .136086-1 | | APPLICATION NO. | |
| INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary) | | | | APPLICANT Schaepkens et al. | | | |
| | | | | FILING DATE | | GROUP | |
| U.S. PATENT DOCUMENTS | | | | | | | |
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| EXAMINER | | | | | DATE CONSIDERED | | |
| Examiner: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. | | | | | | | |